

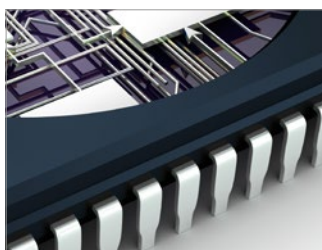


Version: 24 March 2025



PALLUNA[®] 452

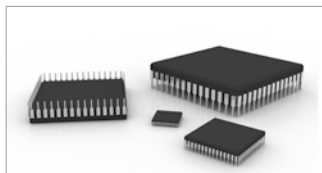
PALLADIUM ELECTROLYTE



Pure palladium electrolyte with excellent bonding and solderability

PALLUNA[®] 452 is a weakly ammoniacal electrolyte for the deposition of palladium in continuous systems and rack plating. It is used especially where excellent bondability and solderability are required.

The electrolyte has already been used for years in semiconductor technology and is mainly used in selective high-speed deposition. It is particularly suitable for systems with immersion cells, belt cells, brush cells, jet and spot systems.



Advantages

- Excellent bonding and solderability
- High deposition rate
- Simple electrolyte feed
- For continuous lines and rack plating

Applications

- Lead frames

PALLUNA® 452

PALLADIUM ELECTROLYTE

TECHNICAL SPECIFICATIONS

| Electrolyte characteristics | | Coating characteristics | |
|---|--|-------------------------|------------------------------|
| Electrolyte type | weakly ammoniacal | Coating | Pure palladium |
| Metal content | 3 (2.5 - 7) g/l Pd | Purity of deposit | 99.9 wt.% Pd |
| pH value | 8.0 (7.5 - 8.4) | Color of deposit | white |
| Temperature | 55 (50 - 60) °C | Brightness | matt |
| Current density range (depending on equipment) | 1 - 2 A/dm ² | Max. coating thickness | approx. 0.3 µm |
| Plating speed | ca. 0.25 µm/min bei 1 A/dm ² ca. 0.50 µm/min bei 2 A/dm ² | Density | approx. 12 g/cm ³ |
| Anode material | PLATINODE® 167 | | |

YOUR CONTACT

Do you have a specific question or would you like a no-obligation quote calculation?
Our specialist will be happy to help you with any technical questions you might have.



Markus Legeler
Manager Sales International

Mail: markus.legeler@eu.umicore.com
Phone: +49 (0) 7171 607 - 204

